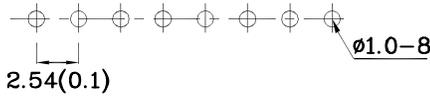


Features

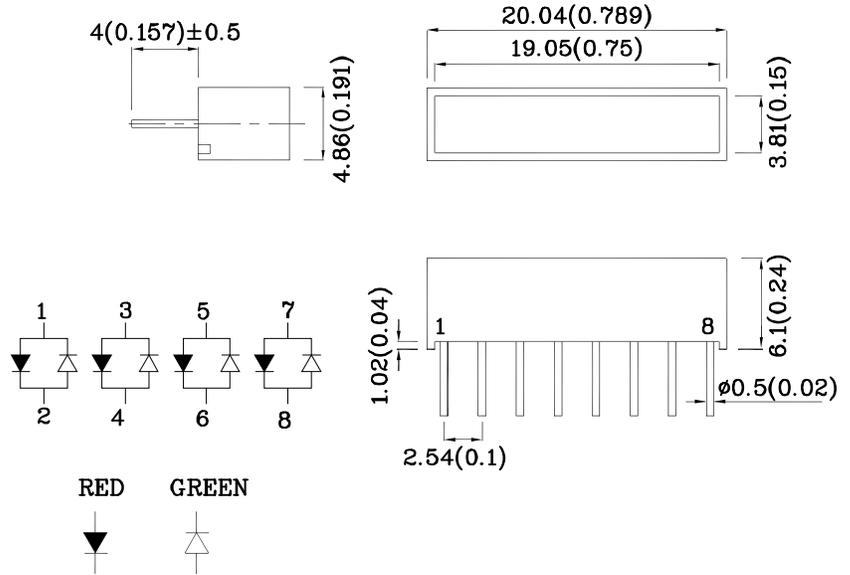
- Robust package
- Uniform light disbursement
- Ideal for backlighting logos or icons
- Excellent for flush mounting
- RoHS compliant



RECOMMENDED PCB LAYOUT



Package Schematics



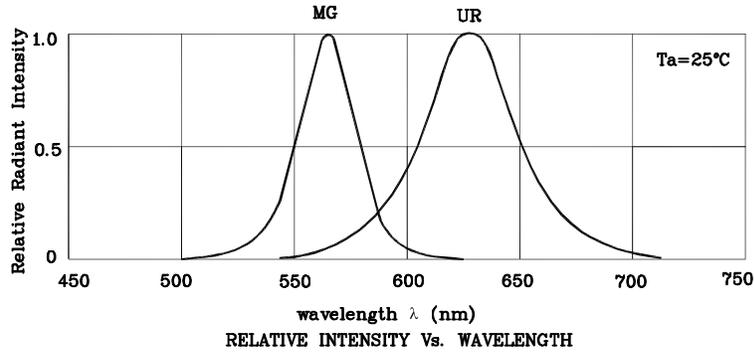
Notes:

1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
2. Specifications are subject to change without notice.

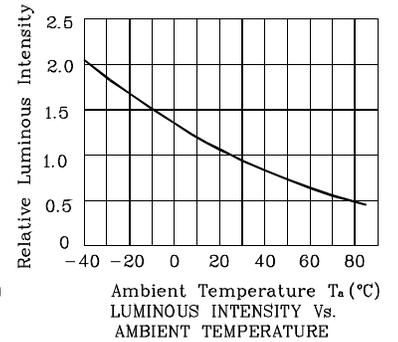
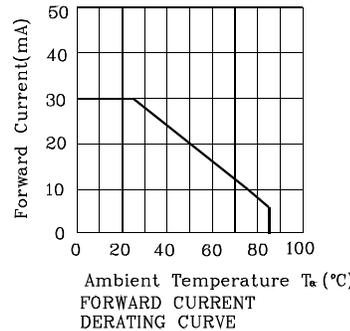
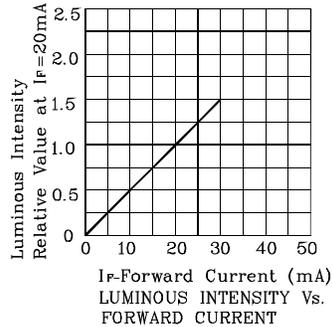
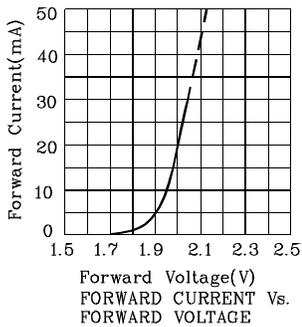
Absolute Maximum Ratings ($T_A=25^\circ\text{C}$)		UR (GaAsP/GaP)	MG (GaP)	Unit
Reverse Voltage	V_R	5	5	V
Forward Current	I_F	30	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	160	140	mA
Power Dissipation	P_D	75	62.5	mW
Operating Temperature	T_A	-40 ~ +85		°C
Storage Temperature	T_{stg}	-40 ~ +85		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds			

Operating Characteristics ($T_A=25^\circ\text{C}$)		UR (GaAsP/GaP)	MG (GaP)	Unit
Forward Voltage (Typ.) ($I_F=20\text{mA}$)	V_F	2	2.2	V
Forward Voltage (Max.) ($I_F=20\text{mA}$)	V_F	2.5	2.5	V
Reverse Current (Max.) ($V_R=5\text{V}$)	I_R	10	10	μA
Wavelength of Peak Emission (Typ.) ($I_F=20\text{mA}$)	λ_P	627	565	nm
Wavelength of Dominant Emission (Typ.) ($I_F=20\text{mA}$)	λ_D	625	568	nm
Spectral Line Full Width At Half-Maximum (Typ.) ($I_F=20\text{mA}$)	$\Delta\lambda$	45	30	nm
Capacitance (Typ.) ($V_F=0\text{V}$, $f=1\text{MHz}$)	C	15	15	pF

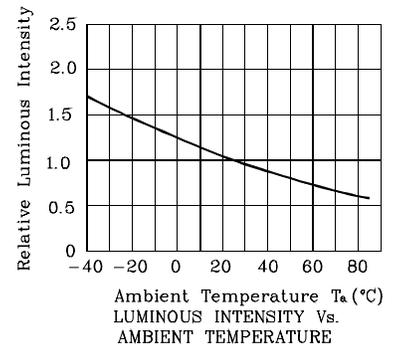
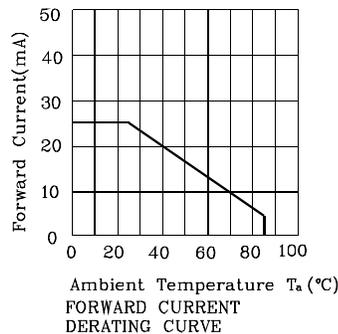
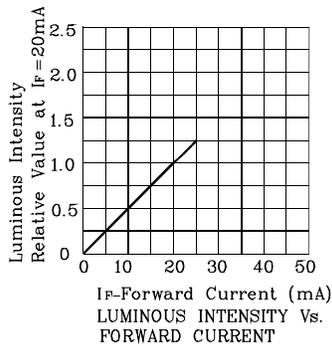
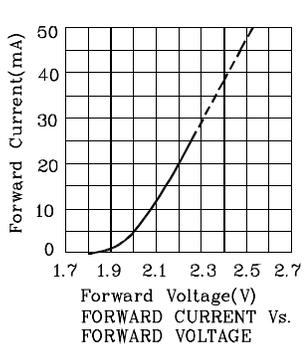
Part Number	Emitting Color	Emitting Material	Luminous Intensity ($I_F=20\text{mA}$) mcd		Wavelength nm λ_P	Lens
			min.	typ.		
XEURMG2350M	Red	GaAsP/GaP	20	49	627	White Diffused
	Green	GaP	40	62	565	



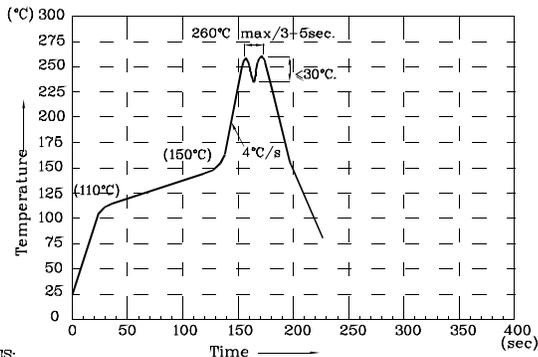
❖ UR



❖ MG



Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



NOTES:

1. Recommend the wave temperature $245^\circ\text{C}\sim 260^\circ\text{C}$. The maximum soldering temperature should be less than 260°C .
2. Do not apply stress on epoxy resins when temperature is over 85°C .
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. During wave soldering, the PCB top-surface temperature should be kept below 105°C .
5. No more than once.

Remarks:

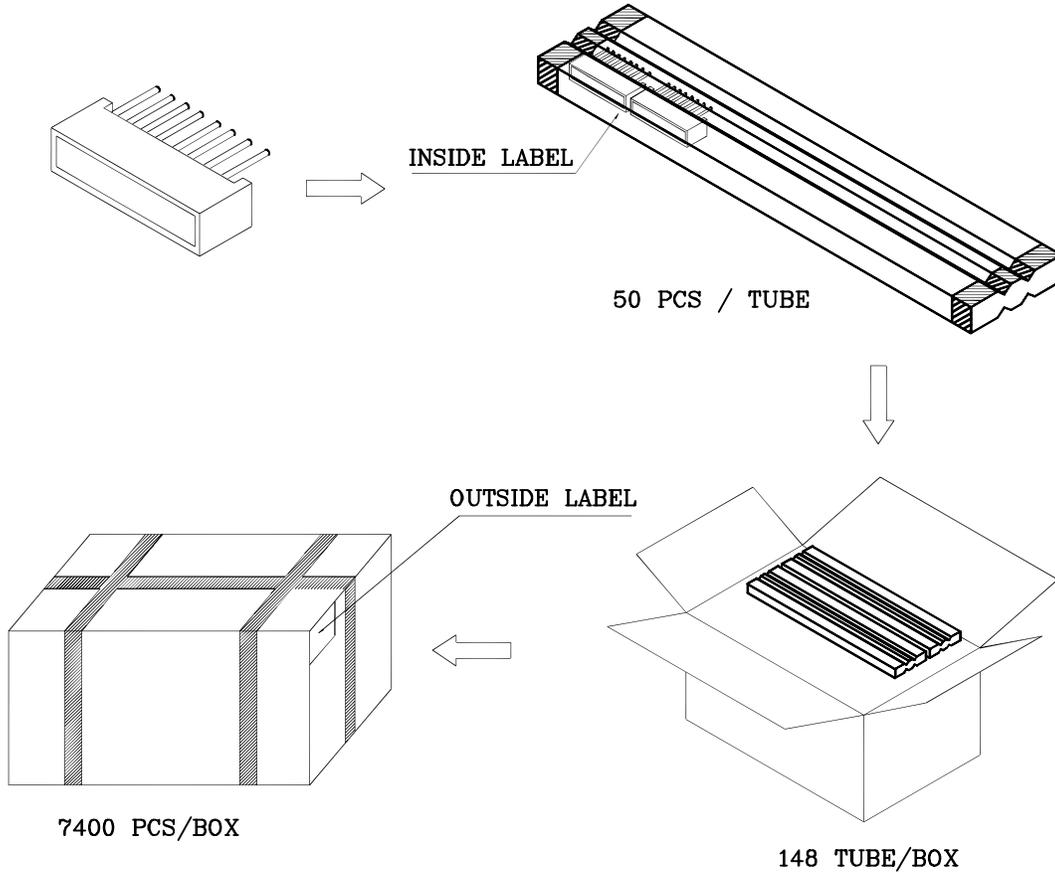
If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: $\pm 1\text{nm}$
2. Luminous Intensity / Luminous Flux: $\pm 15\%$
3. Forward Voltage: $\pm 0.1\text{V}$

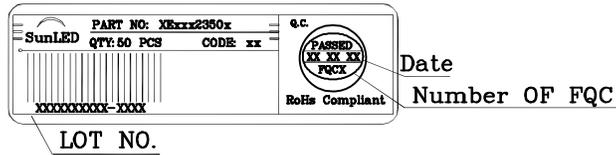
Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS



Inside Label On IC-tube



Outside Label On Box

